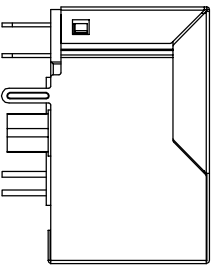
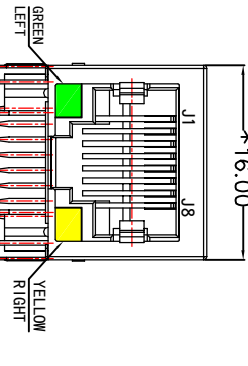


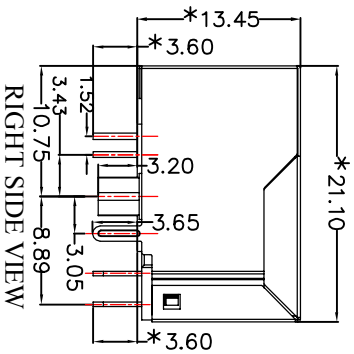
TOP VIEW



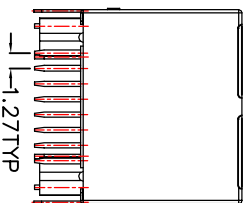
LEFT SIDE VIEW



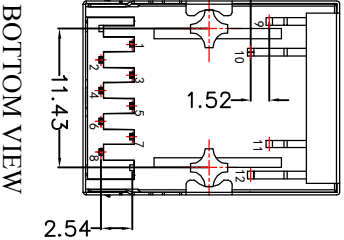
FRONT VIEW



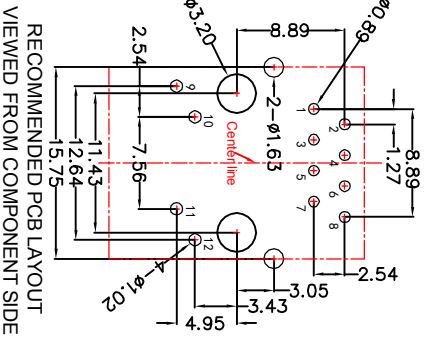
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
 6U" GOLD PLATING ON CONTACT AREA.

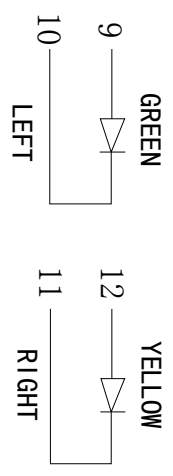
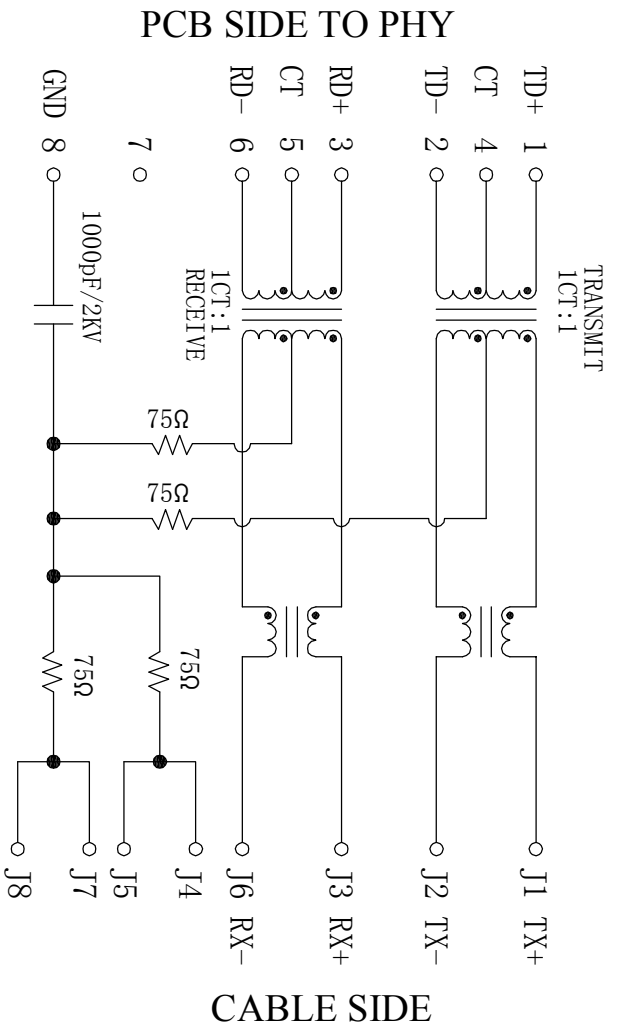
MECHANICAL:

DURABILITY: 750 CYCLES MIN.
 MATING FORCE: 23N MAX.
 OPERATING TEMPERATURE: -40°C~+85°C.
 STORAGE TEMPERATURE: -40°C~+85°C.
 ALL CRITICAL DIMENSIONS WITH "±"

CELLION SAS

DESCRIPTION		TAB-DOWN 1X1 100BASE		
DRAWING NO		PART NO	R145111B002CA1D	
THIRD ANGLE PROJECTION	REVISION	UNIT		
	A	MM	X±0.35	X°±3.0°
CHECKED	DRAWN	SCALE	X±0.30	X°±2.0°
	SHEET	1/1	X±0.25	X±1.5°

1 2 3 4 5



x40.30

Electrical:

1. Turn Ratio: 1~2:J1~J2=1CT:1CT(±2%).
3~6:J3~J6=1CT:1CT(±2%).
2. OCL: 350uH Min. at 100KHz 100mV 8mA DC.
3. Insertion Loss: -1.0 dB Max 1~100MHz.
4. Return loss: -18dB Min 1~30MHz;
-14dB Min 30~60MHz;
-10dB Min 60~100MHz.
5. Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
6. CMR: -35dB Min 1~100MHz;
7. Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

LED Specification

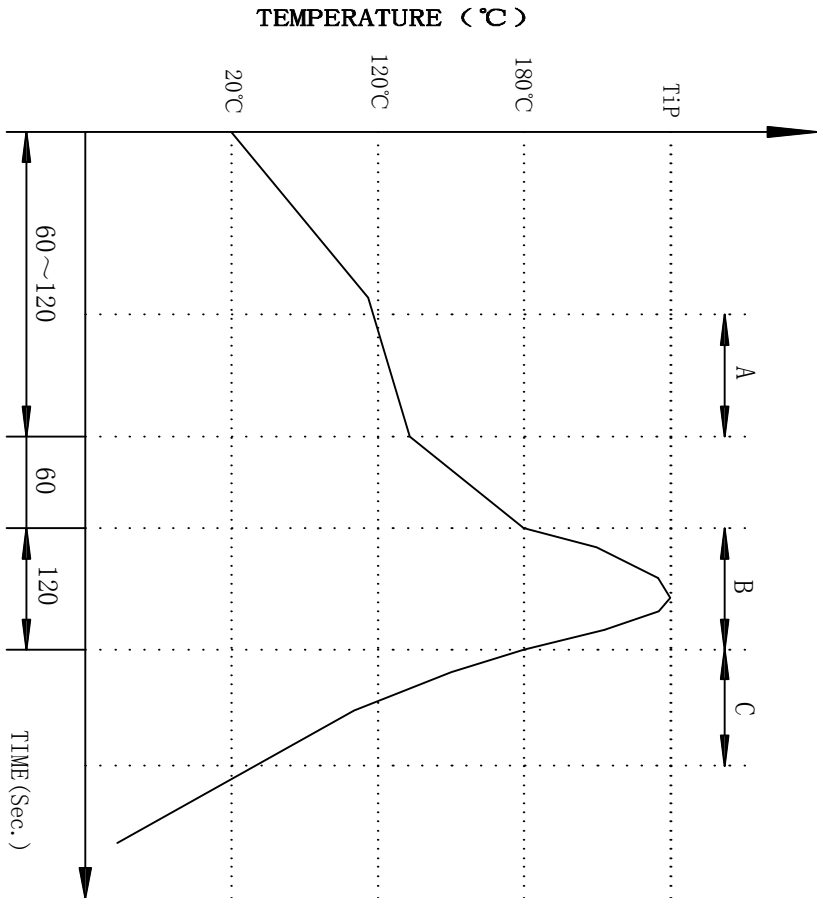
Standard LED Color	LED Wavelength	Forward(A)	Forward(V)
Green	568nm	20mA	1.85-2.45V
Yellow	585nm	20mA	1.7-2.2V

CELLION SAS

DESCRIPTION		TAB-DOWN 1X1 100BASE			
DRAWING NO		PART NO	R45111B002CA1D		
THIRD ANGLE PROJECTION	REVISION	A	UNIT	MM X40.35	
	SCALE	N/A			
	SHEET	1/1			



PROFILE OF WAVE SOLDER



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

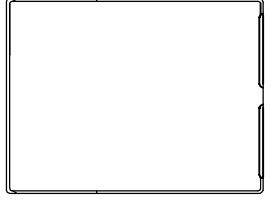
Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

CELLION SAS

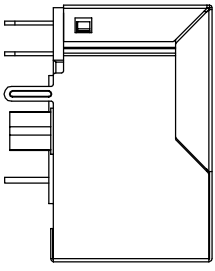
DESCRIPTION		TAB-DOWN 1X1 100BASE		
DRAWING NO	PART NO	R1451118002CA1D		
THIRD ANGLE PROJECTION	REVISION	A	UNIT	MM
	SCALE	N/A		
	SHEET	1/1		

REACH & RoHS COMPLIANT

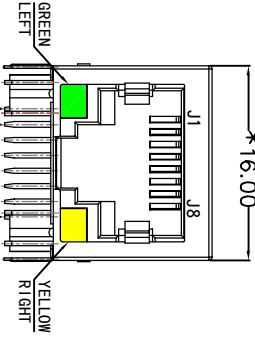
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	ZG.Hu	2018.07.05



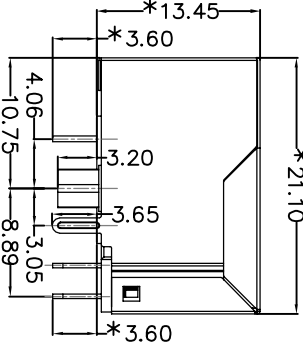
TOP VIEW



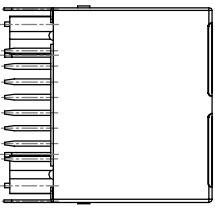
LEFT SIDE VIEW



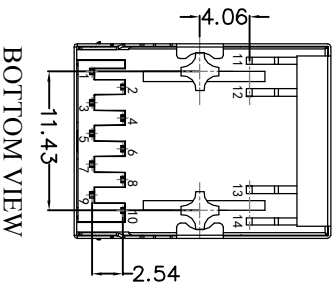
FRONT VIEW



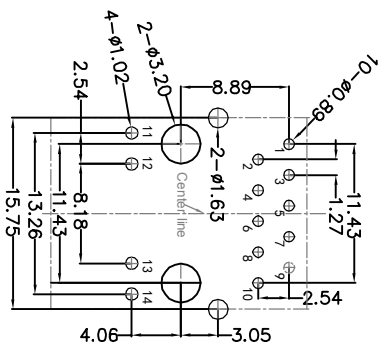
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
 6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

DURABILITY: 750 CYCLES MIN.
 MATING FORCE: 23N MAX.
 OPERATING TEMPERATURE: -40°C~+85°C.
 STORAGE TEMPERATURE: -40°C~+85°C.
 ALL CRITICAL DIMENSIONS WITH "*"!

TITLE: TAB-DOWN IX1 100BASE POE	SIZE	A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY: JP.Gong			
	PART NO.:	111B073AB2A1DP				SAGLE	1:1	CHECKED BY: TW.Xu
	REMARK:					REV	A0	DESIGND BY: ZG.Hu
	REMARK:					SHEET	1/3	

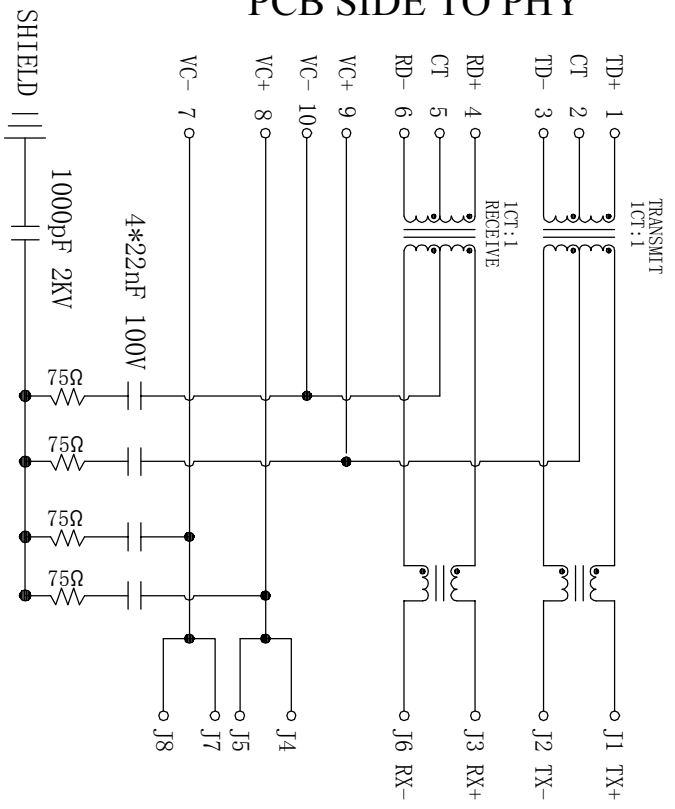
CELLION SAS

1 2 3 4 5 6 7 8

REACH & RoHS
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	ZG.Hu	2018.07.05

PCB SIDE TO PHY



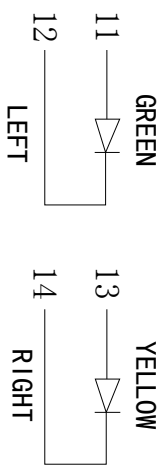
CABLE SIDE

Electrical:

- Turn ratio: 1~3:J1~J2=1CT:1CT(±2%).
4~6:J3~J6=1CT:1CT(±2%).
 - OCL: 350uH Min. @ 100KHz 100mV
RMS(4Channel) 8mA DC BIAS.
 - Insertion Loss: -1.0 dB Max 1~100MHz.
 - Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz;
-12dB Min 30~60MHz;
-10dB Min 60~80MHz.
 - Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
 - CMR: -30dB Min 1~100MHz;
 - Hi-Pot: 1500V AC & 2250V DC 6S 1mA PRI TO SEC
 - Single port magnetic jack POE magnetics acc.
- To IEEE802.3af for PSE or PD applications.
9. 100% of production tested to comply with
IEEE 802.3 isolation equipments balanced DC
line current 350mA max. 57V DC continuous.

LED Specification

Standard LED Color	LED Wavelength	Forward(A)	Forward(V)
Green	568nm	20mA	1.85-2.45V
Yellow	585nm	20mA	1.7-2.2V



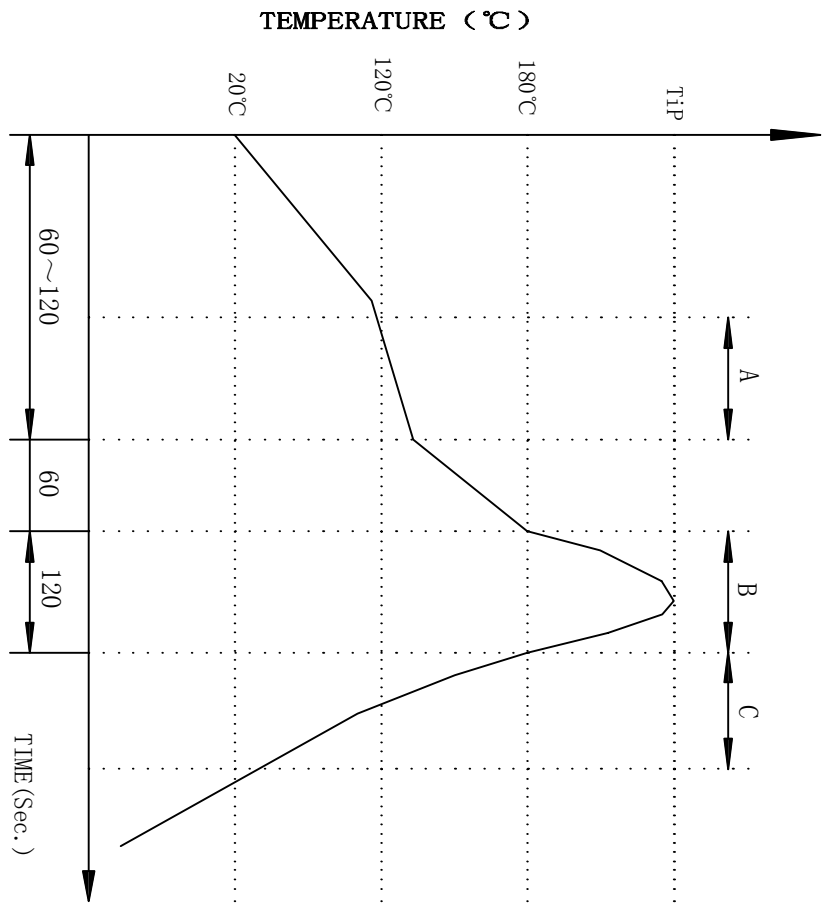
TITLE: TAB-DOWN IX1 100BASE POE PART NO.: 111B073AB2A1DP REMARK:	SIZE	UNITS	GENERAL TOLERANCES		APPROVED BY:
	A4	MM[INCH]	UNLESS SPECIFIED		JP.Gong
	SACLE 1:1	REV A0	X±0.35	X°±3.0°	CHECKED BY: TW.Xu DESIGND BY: ZG.Hu
	SHEET 2/3		.X±0.30	X°±2.0°	
		.XX±0.25	.XX°±1.5°		
			.XXX±0.10	.XXX°±1.0°	

CELLION SAS

REACH & RoHS
COMPLIANT

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	ZG,Hu	2018.07.05



A. Preheating B. Soldering C. Gradual Cooling
 Tip temperature: 260±5°C.
 Tip temperature time: 5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5: 217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

TITLE:	SIZE	UNITS	GENERAL TOLERANCES	APPROVED BY:
TAB-DOWN IX1 100BASE POE	A4	MM[INCH]	UNLESS SPECIFIED	JP.Gong
PART NO.:	SACLE	REV	X±0.35	CHECKED BY:
111B073AB2A1DP	1:1	A0	X±0.30	TW.Xu
REMARK:	SHEET		.XX±0.25	DESIGND BY:
	3/3		.xxx±0.10	ZG,Hu

CELION SAS

A